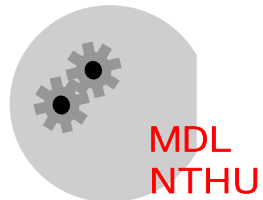
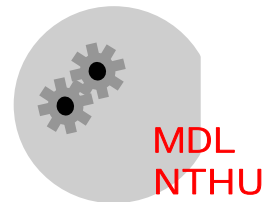


1.2 Historical Background

- **Microelectronics**
 - + **1947** - first transistor invented at Bell Lab
 - + **1959** - first IC invented by Kilby
 - + **1961** - first commercial IC fabricated by Fairchild and Texas Instruments
 - + **1969** - LSI, 1000 ~ 10000 components/chip
 - + **1975** - VLSI, more than 10000 components/chip
 - + **Present** – ULSI
 - 0.35 μ m to 0.25 μ m to 0.18 μ m to ...
 - 5in to 6in to 8in to 12in



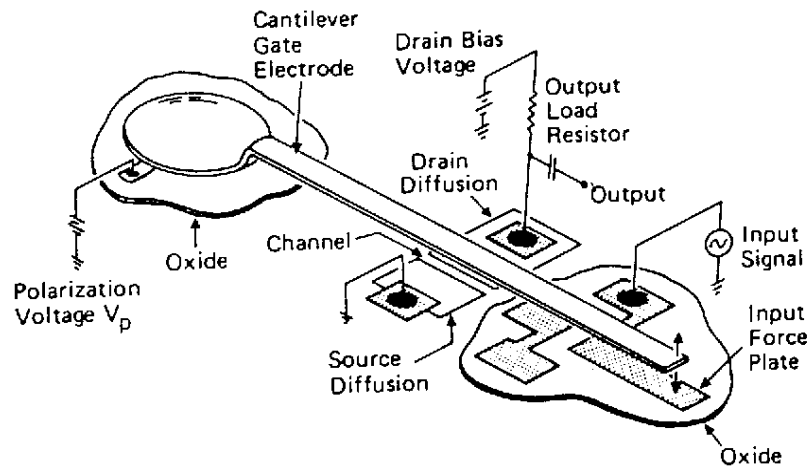
Planar Technology



- **IC : TSMC, UMC, Winbond, ...**
- **Magnetic recording head : Seagate, Quantum, ...**
- **LED/VCSEL/Diode laser : Opto tech, Metrodyne**
- **TFT-LCD : AU Optronics, Quanta Display, ...**
- **MEMS : Walsin Lihwa, APM, Neostone, ...**

- **Micromachining**

+ **1965 - concept of (surface) micromachining from resonant gate transistor**



H.C. Nathanson and R.A. Wickstrom, Applied Physics Letter, 1965.

+ **1966 - silicon membrane fabricated by back side etch**

R.J. Jaccodine and W.A. Schlegel, J. of Applied Physics, 1966.

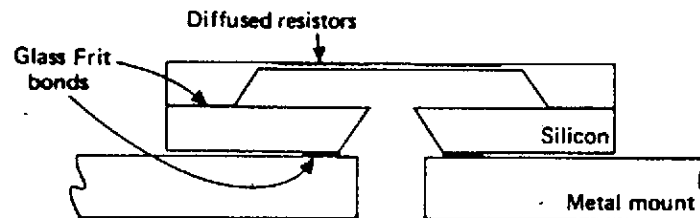
+ **1967 - anisotropic etching**

R.M. Finne and D.L. Klein, J. of Electrochemical Society, 1967.

+ 1972 - silicon micromachined beams

S.C.H. Lin and I. Pugacz-Muraszkiewicz, *J. of Applied Physics*, 1972.

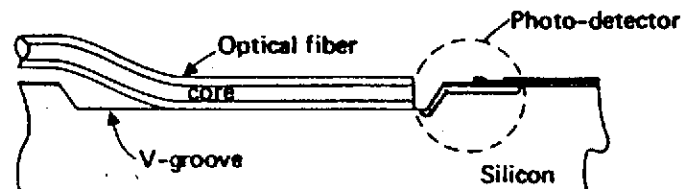
+ 1974 - pressure transducer



A.C.M. Gieles and G.H.J. Somers, *Philips Tech. Rev.*, 1973.

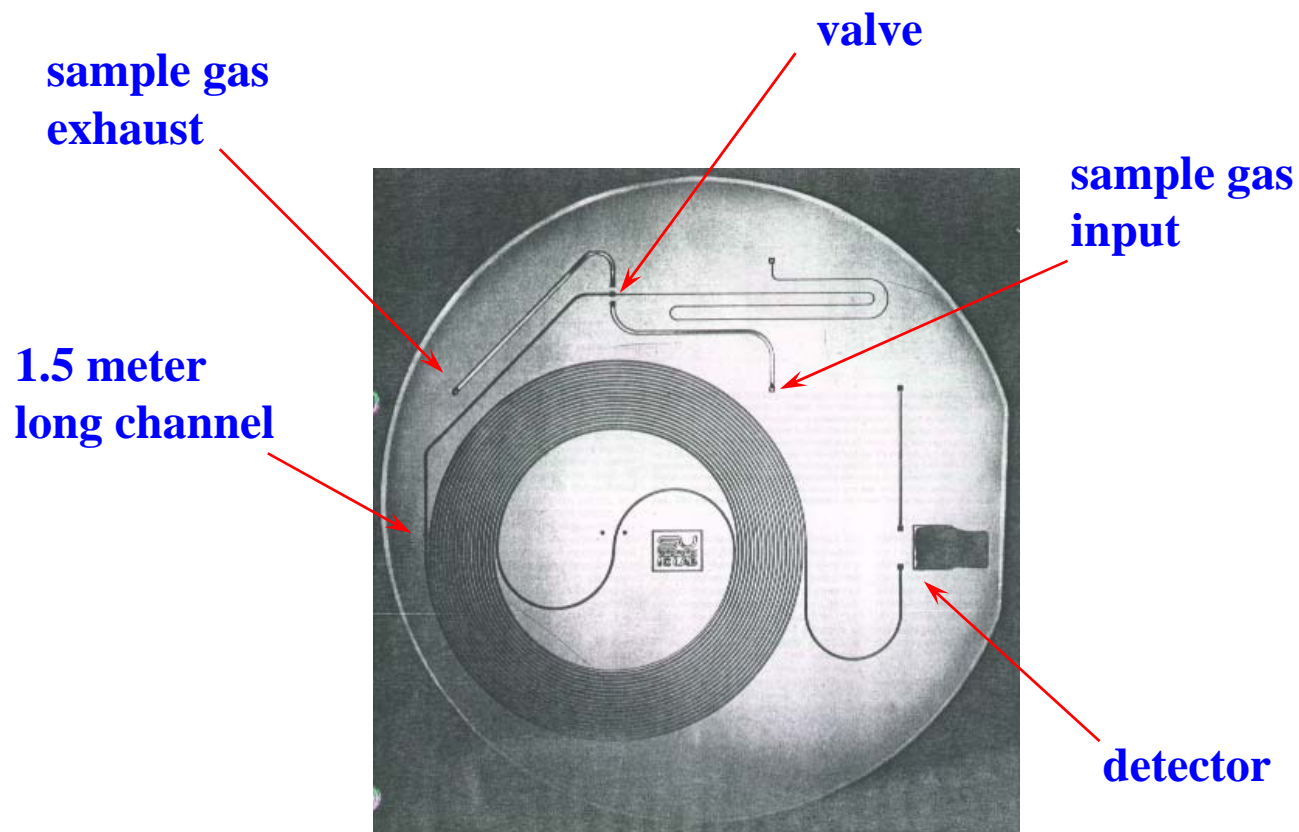
Figure source: K.E. Petersen, *Proceeding of the IEEE*, 1982.

+ 1974 - optical fiber alignment (groove)



L.P. Boivin, *Applied Optics*, 1974.

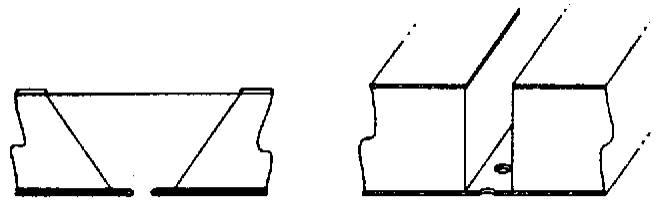
+ 1975 - gas chromatograph (groove, hole, bonding)



S.C. Terry, Ph.D. thesis, 1975.

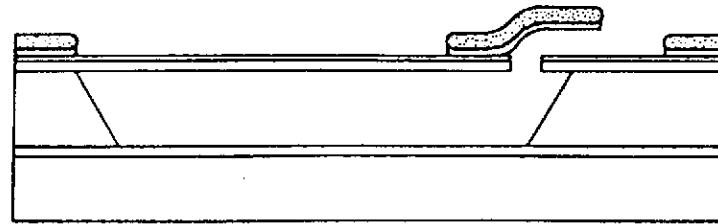
S.C. Terry, J.H. Jerman and J.B. Angell, IEEE Transaction on ED, 1979.

+ 1977 - ink jet nozzles (nozzle)

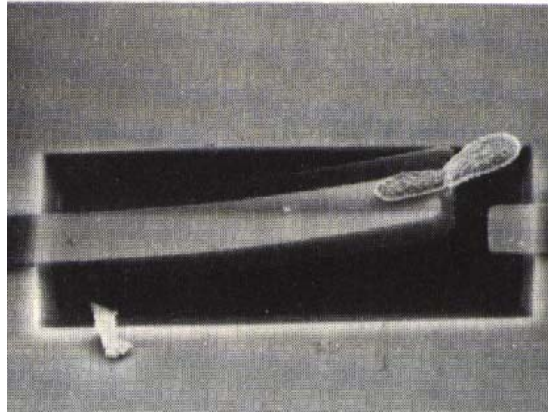


E. Bassous, L. Kuhn, A. Reisman, and H.H. Taub, U.S. Patent 4 007 464, 1977.

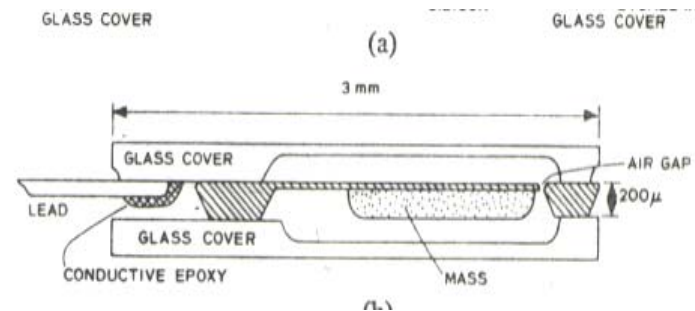
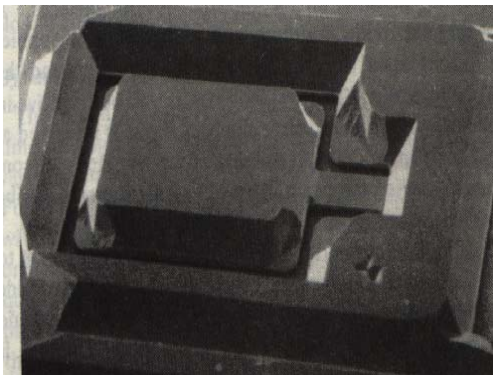
+ 1978 - electrical switch (cantilever beam)



K.E. Petersen, IEEE Transaction on ED, 1978.

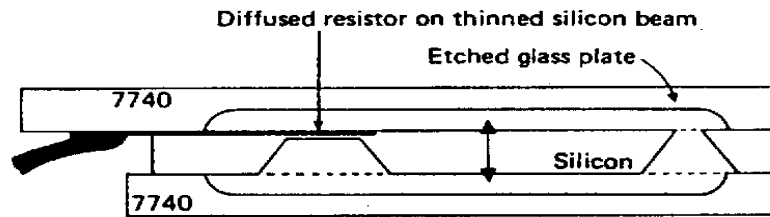


K.E. Petersen, IEEE Transaction on ED, 1978.



L.M. Roylance and J.B. Angell, IEEE Transaction on ED, 1979.

+ 1979 - accelerometer (cantilever beam)

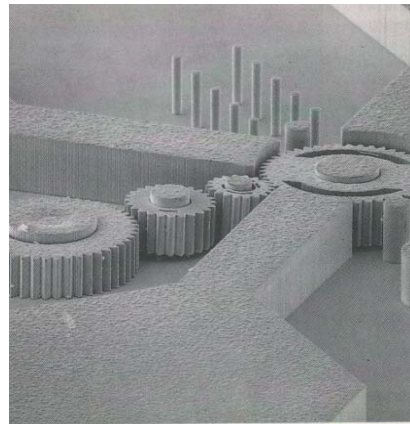


L.M. Roylance and J.B. Angell, IEEE Transaction on ED, 1979.

+ 1982 - **silicon micromachining** named by Petersen

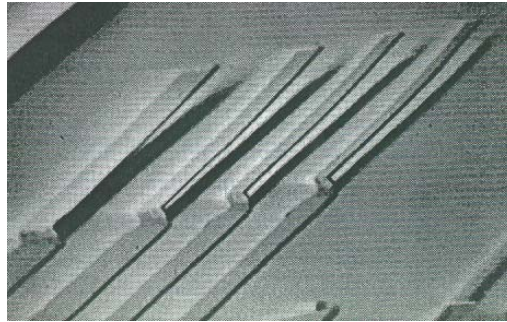
K.E. Petersen, Proceeding of the IEEE, 1982.

+ 1982 - **LIGA** process developed by Becker et. al.



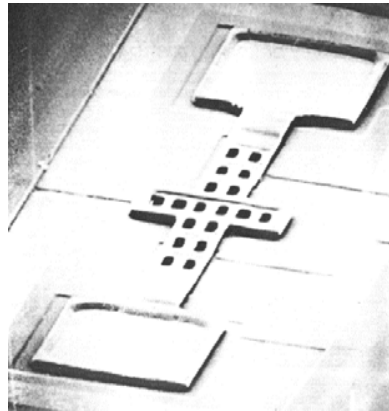
E.W. Becker, et al., Naturwissenschaften, 1982.
Figure source: J. Bryzek, K. Petersen, and W. McCulley IEEE Spectrum, 1994.

+ 1983 - **surface micromachining** re-developed by Howe



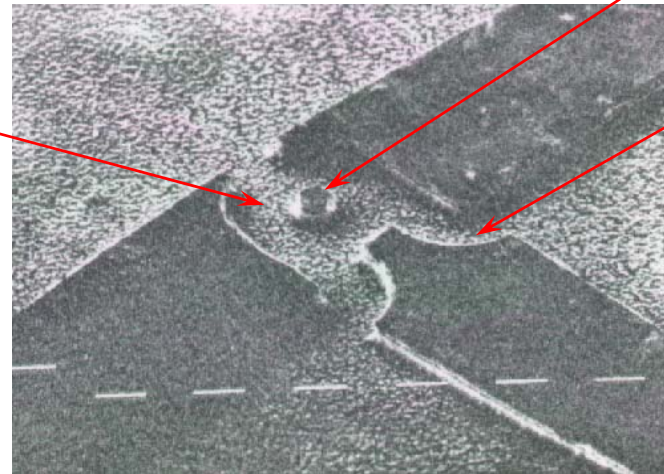
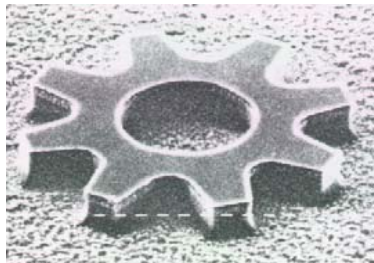
R.T. Howe and R.S. Muller, *J. of Electrochemical Society*, 1983.

+ 1986 - **surface micromachined resonant microbridge**



R.T. Howe, and R.S. Muller, *IEEE Trans. on Electronic Devices*,
ED-33, pp. 499-506, 1986

+ 1987 - concept of **movable micromachined structures** (turbines) through assembly



spindle

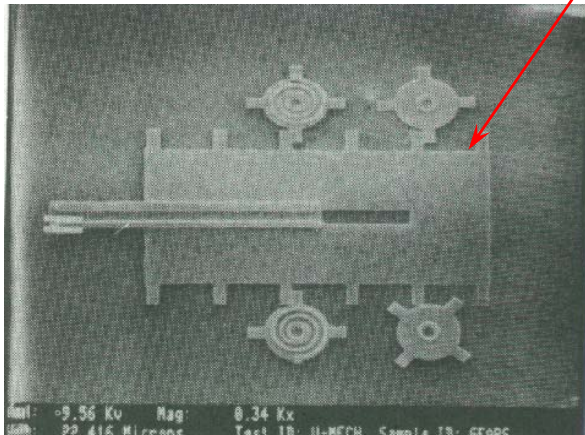
air inlet hole

M. Mehregany, K.J. Gabriel, and W.S.N. Trimmer, *Sensors and Actuators*, 1987

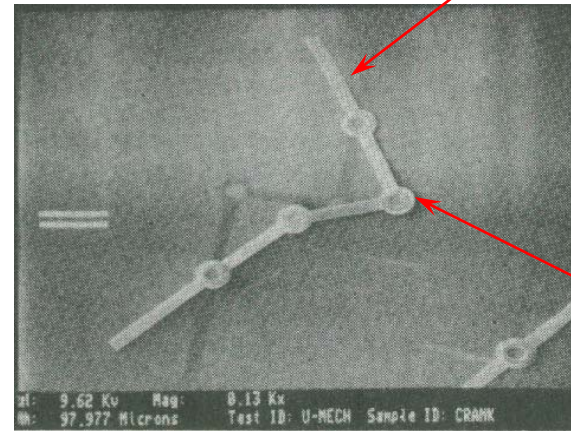
+ 1987 - **MEMS** (Microelectromechanical System) named after three workshops

+ 1988 - first **movable and integrated micromachined structures including sliders, hinges and cranks**

slider



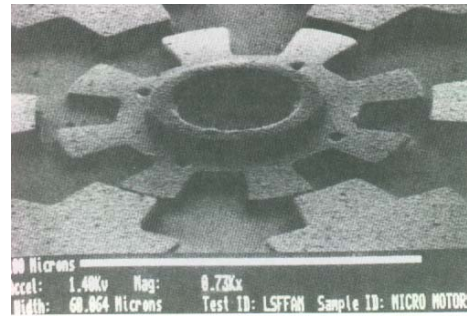
crank



hinge

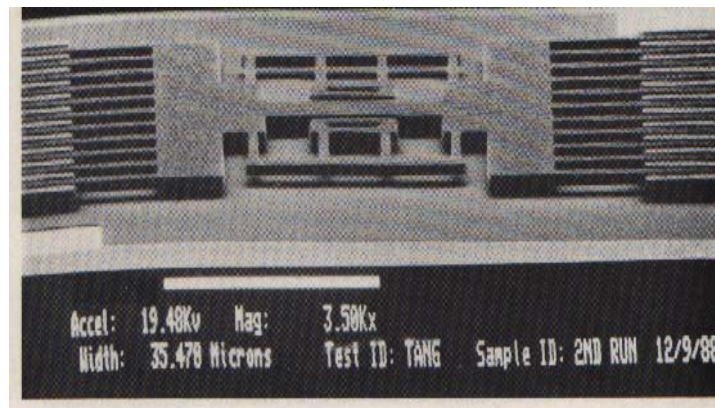
L.-S. Fan, Y.-C. Tai, and R.S. Muller, IEEE Transaction on ED, 1988.

+ 1988 - first micromachined motor



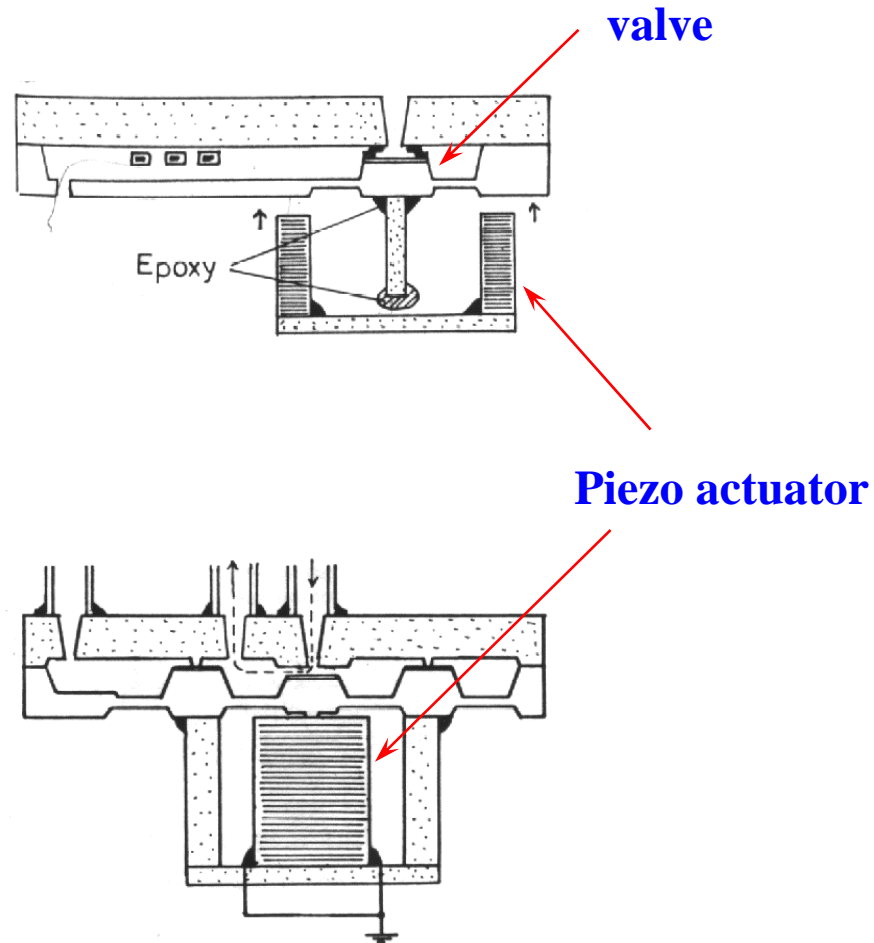
L.-S. Fan, Y.-C. Tai, and R.S. Muller, Int. Electron Devices meeting, 1988.

+ 1989 - first micromachined linear actuator



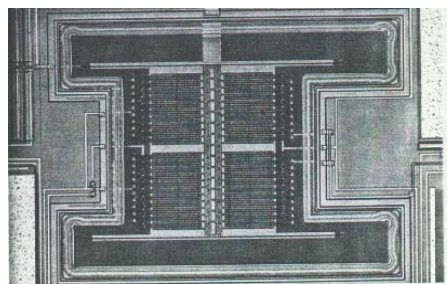
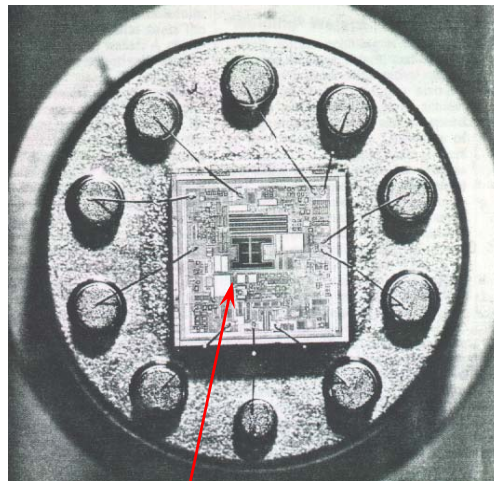
W.C. Tang, T.-C.H. Nguyen, and R.T. Howe, IEEE MEMS Conference, 1989.

+ 1990 - microfluid system attract attention



M. Esashi, Sensors and Actuators, 1990

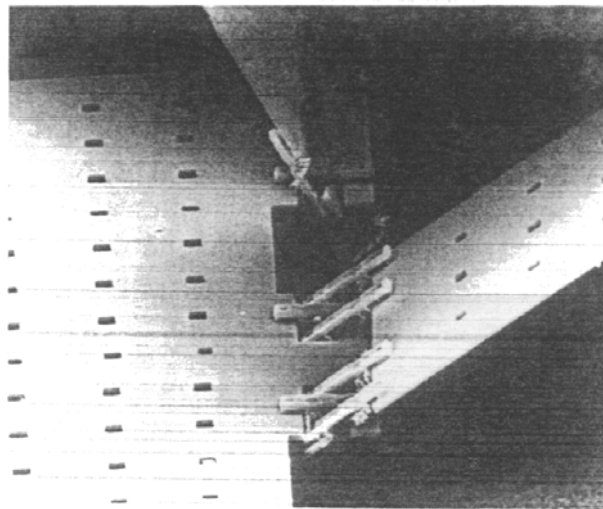
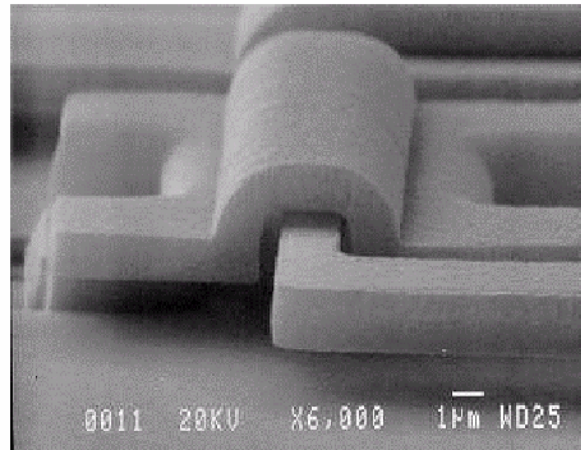
+ 1991 - first commercialized surface micromachined accelerometer introduced by Analog Devices



**mechanical
component**

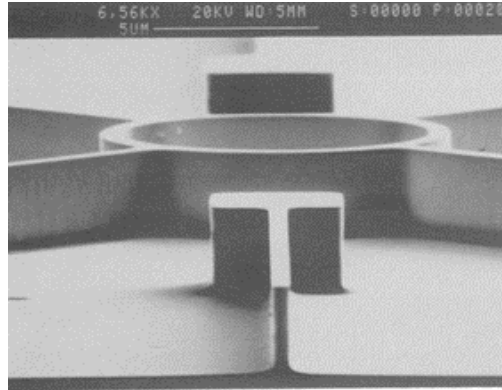
Figure source: L. O'Connor, Mechanical Engineering, 1992.

+ 1992 - micromachined hinge



K. S. J. Pister, Sensors and Actuators A, 1992

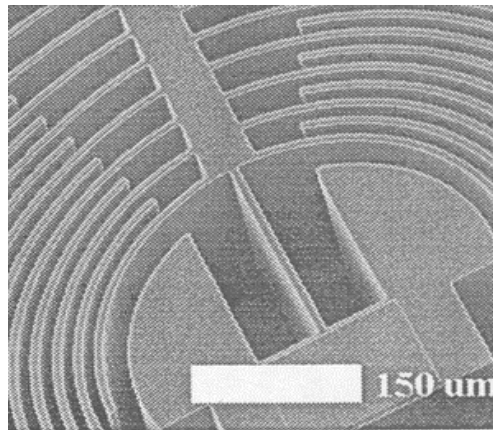
+ 1993 - thick micromachined structures (SCREAM)



4 μm

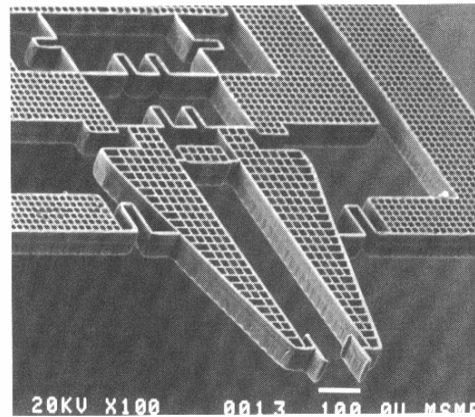
Z.L. Zhang and N.C. MacDonald, J. of MEMS, 1993

+ 1995 - thick micromachined structures (DRIE)



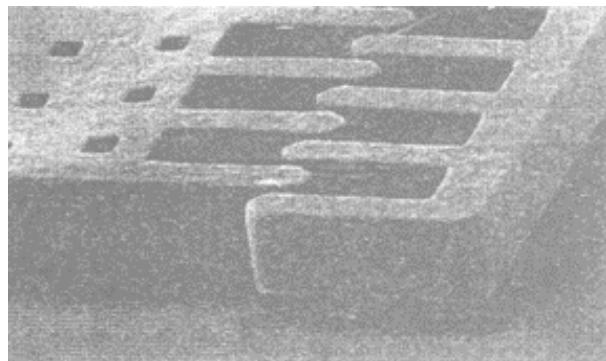
E.H. Klaassen, et.al., Transducers'95, 1995

+ 1995 - thick micromachined structures (Hexsil)



R.T. Howe, J. of MEMS, 1995

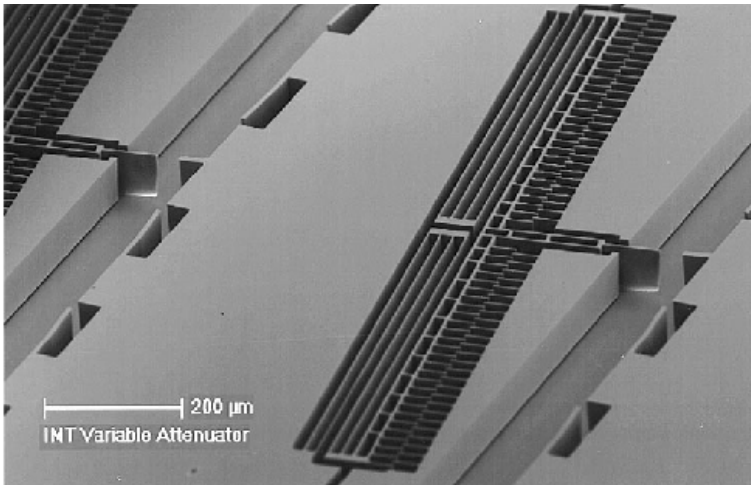
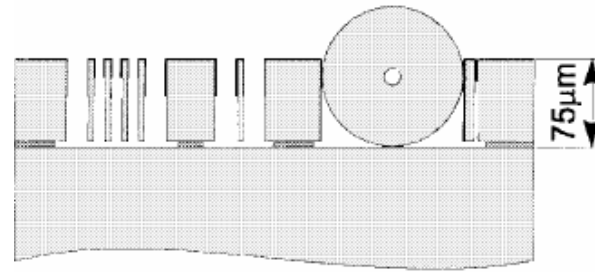
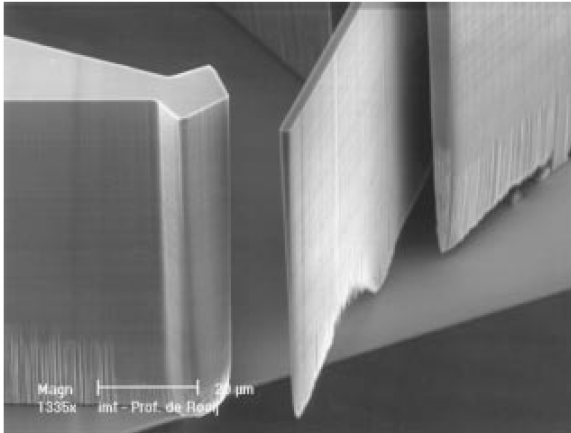
+ 1996 - thick micromachined structures (by etch-diffusion processes)



12 μm

W.-H. Juan and S.W. Pang, J. of MEMS, 1996

+ 1995? - SOI

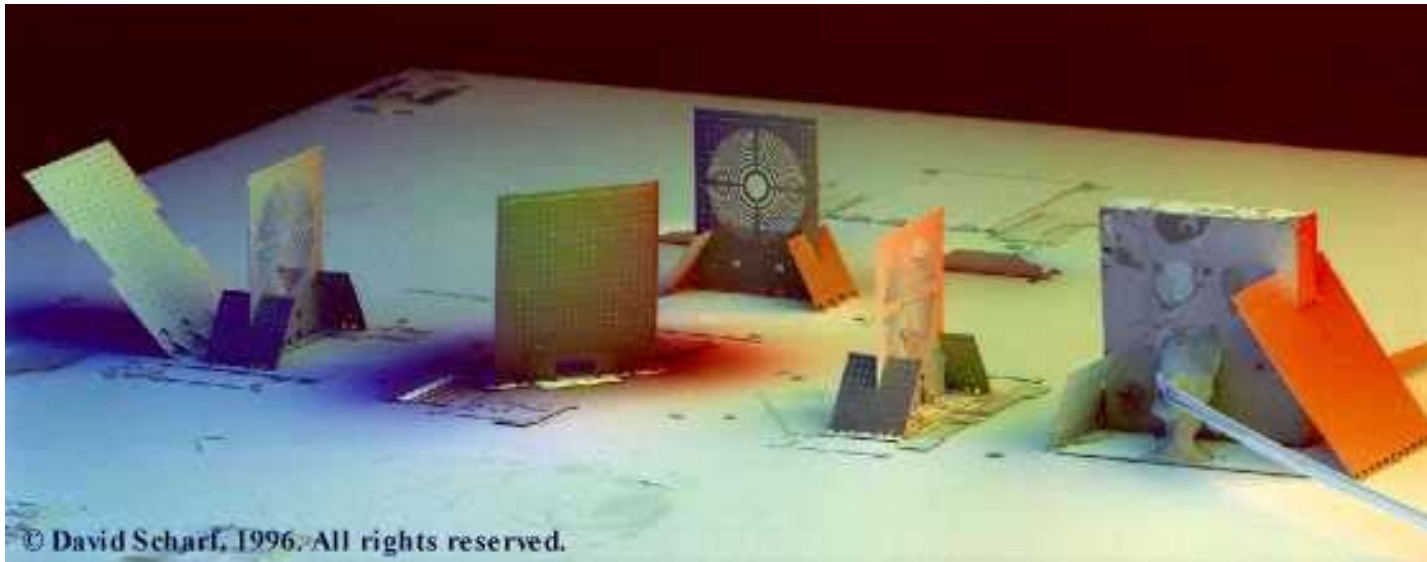


Optical Switch

C. Marxer, N. F. de Rooij, J. MEMS 97

+ 1996 - Optical bench (original idea: M. C. Wu et al. , *Sensors and Actuators A*, 1995)

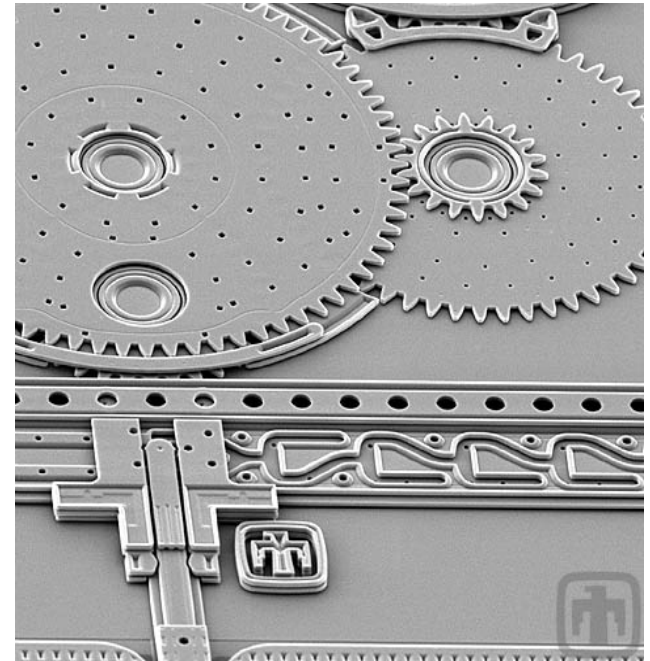
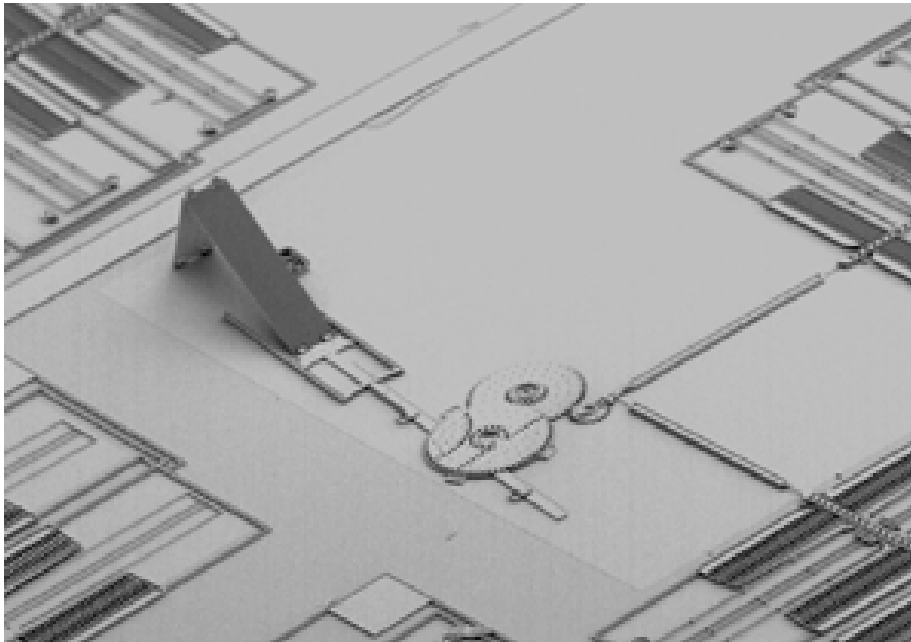
Optical-disk pickup head realized by FSMOB technology :



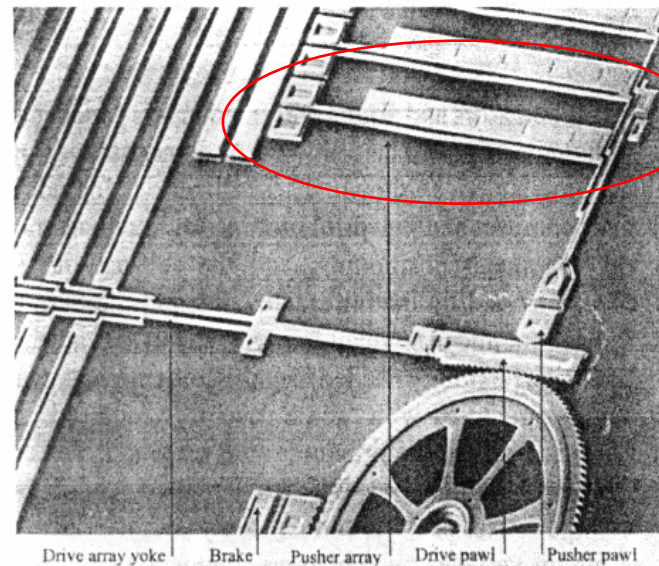
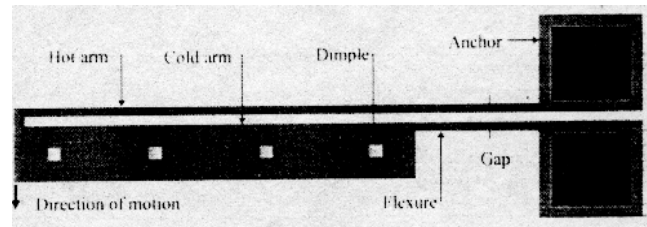
© David Scharf, 1996. All rights reserved.

L. Y. Lin et al. , *Opt. Lett.* , 1996

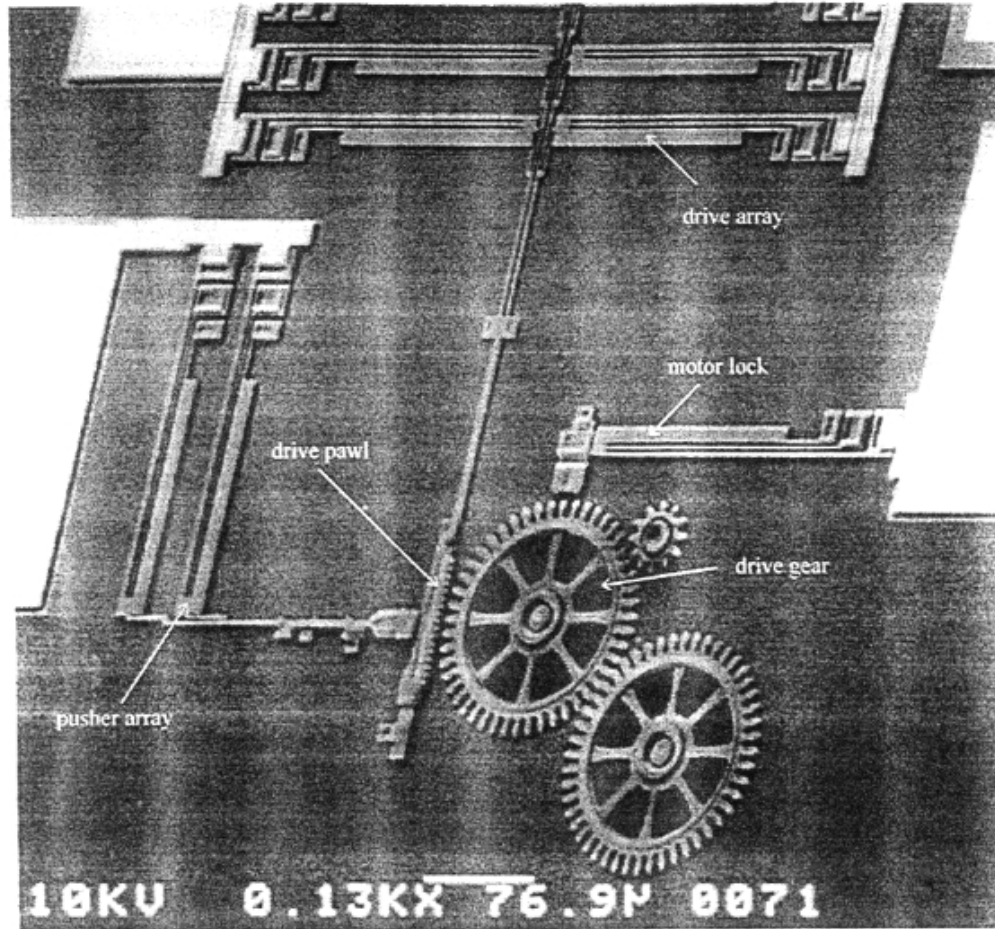
+ 1996? – **SUMMIT** processes by Sandia National Lab, **three layers**
micromachined structures



+ 1997 - complicated mechanism driven by electro-thermal actuators



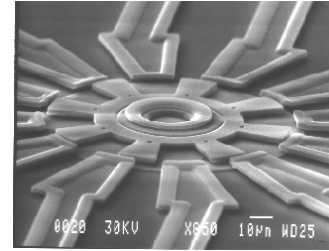
J.H. Comtois and V.M. Bright, Sensors and Actuators A, 1997



D.M. Burns and V.M. Bright, 1997

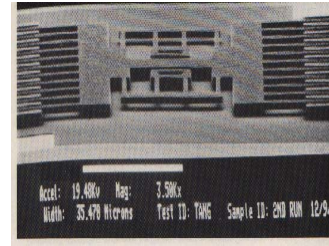
Motor

L.S.Fan, Y.C. Tai, R.S.Muller
(1988)



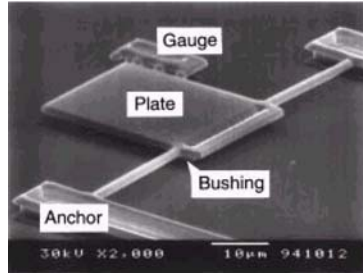
Comb-drive

Tang, Nguyen, Howe
(1989)



Hinge

K.S.J. Pister
(1992)



SDA
Japan
(1992)

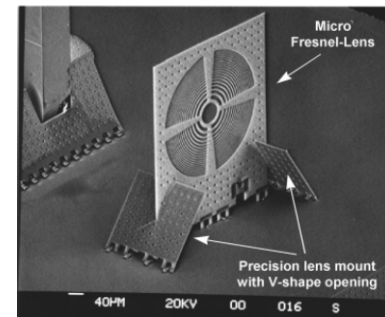
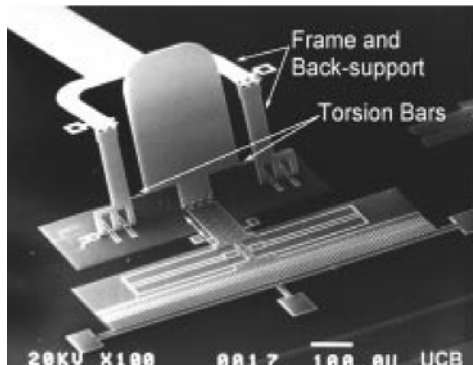
MUMPs (1993)

**Free-Space
Micro-Optical Bench**
UCLA, M.C. Wu, (1995)

**Summit
Summit V**

**Dynamic
Application**
M.H.Kiang, R.S.Muller
(1996)

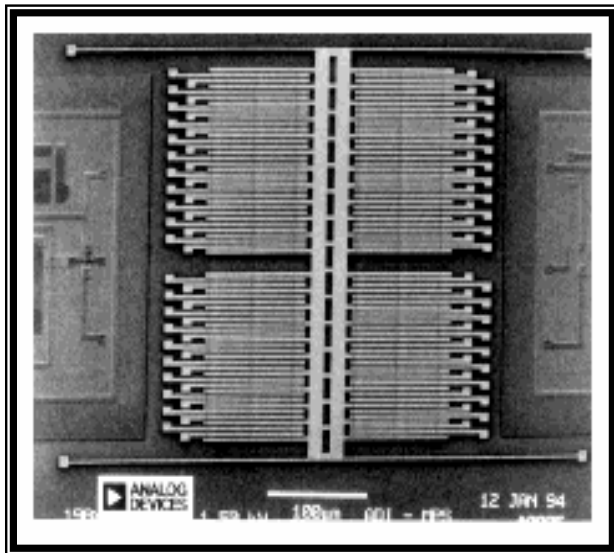
?
(2001~)



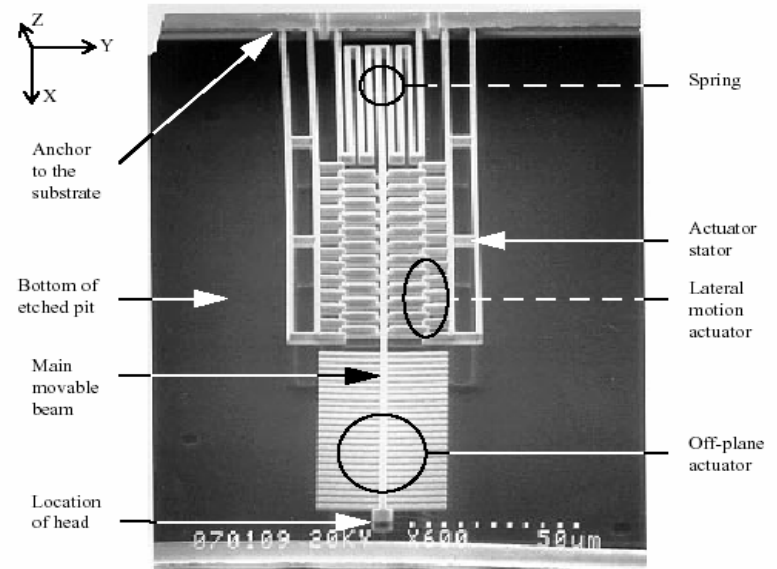
+ 1999? – **SUMMIT V** processes by Sandia National Lab, **five layers**
micromachined structures



+ ? – CMOS MEMS

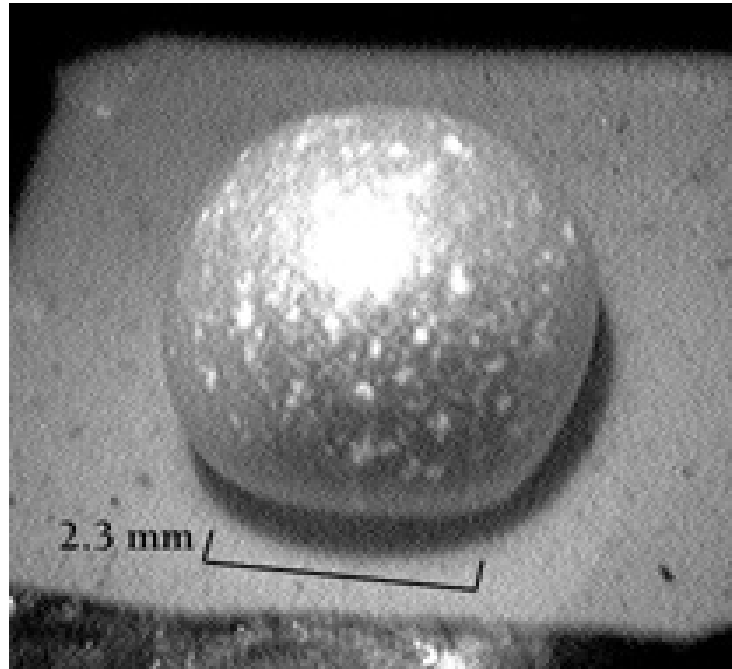


CMOS Based MEMS Accelerometer



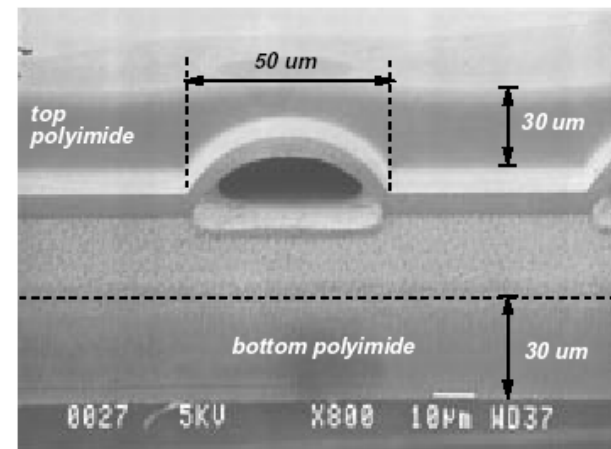
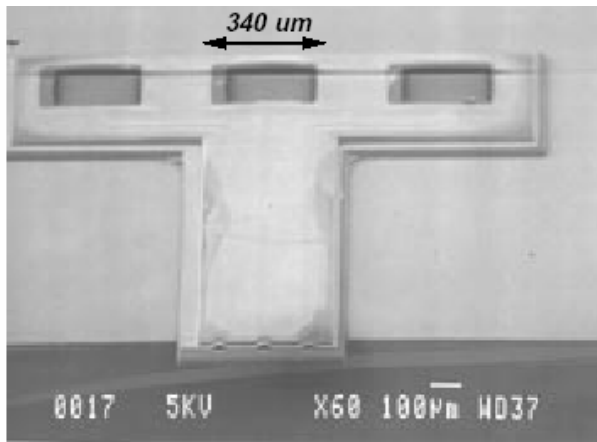
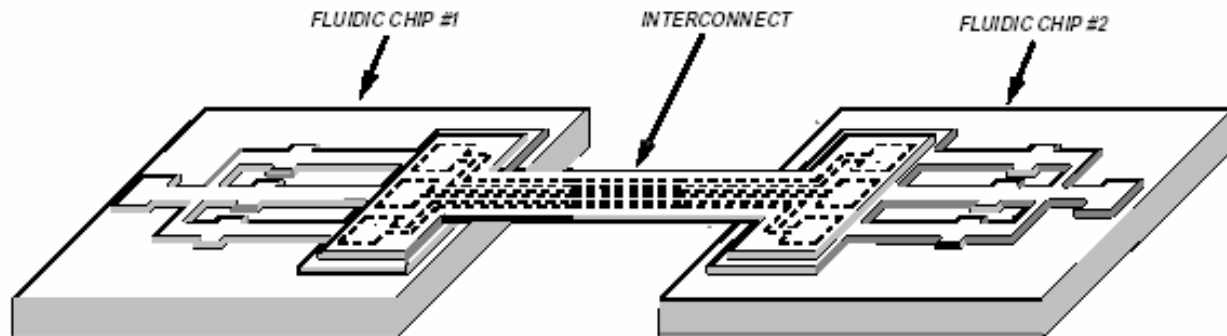
MEMS optical data storage in CMOS process, Japan

+ ? - Polymer MEMS



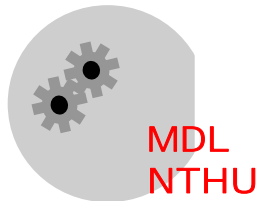
Thermal pneumatic Silicone Membrane Valve, X. Yang et. al., Caltech, 1997

+ ? - Polymer MEMS



Biochip fluidic interconnect, Michigan, USA

MEMS is an enabling technology



- **Miniaturization** - length scale
- **Distribution** - array, multi function
- **Integration** - mechanical and electrical
- **Motion** - moving parts and media

- Evolution of the devices

+ Miniaturization

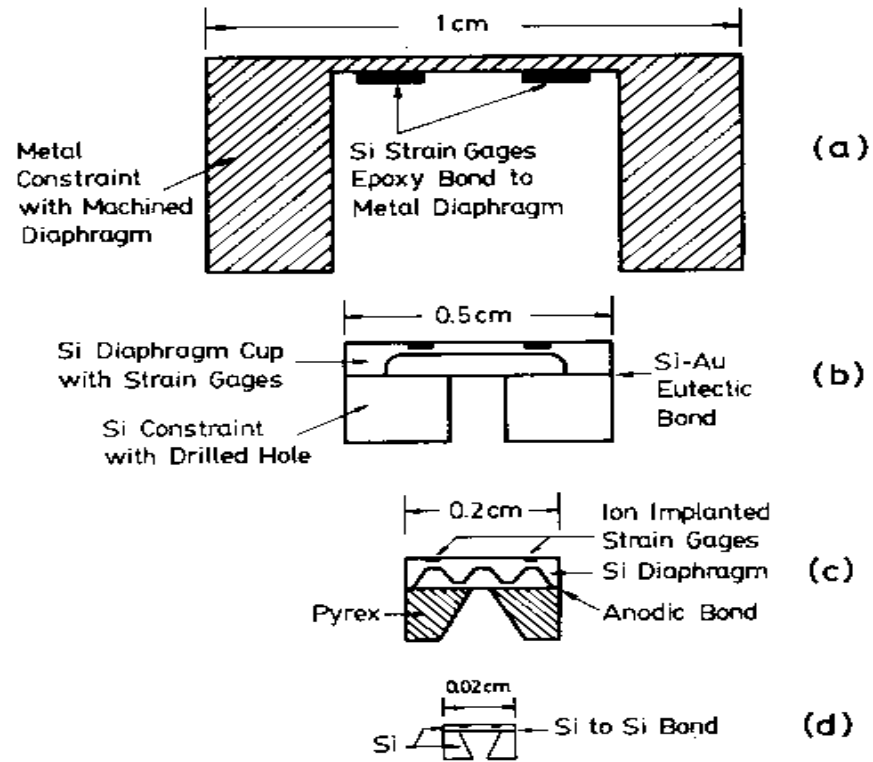
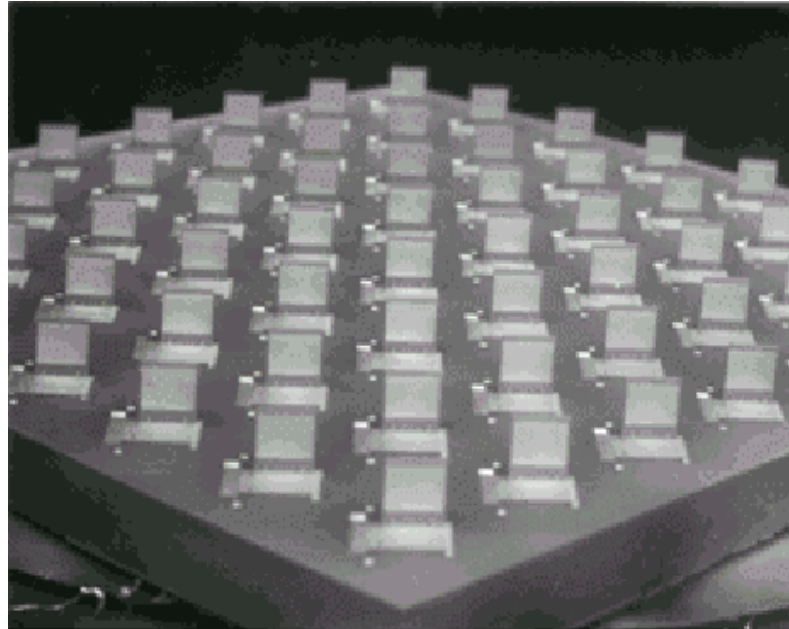


Fig. 5 Evolution of diaphragm pressure sensors. (After Ref. 11)

+ Distribution – integrated machines




Optical switch array by OMM Inc.

酷·驚喜·耶誕 到寶島

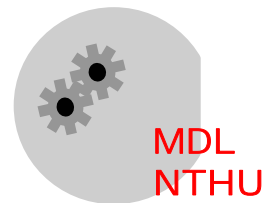
“美玲！妳的呼叫器呢？”

“親愛的！我把呼叫器藏在手錶裡”

 寶島鐘錶公司

總公司：台北市漢口路81號
服務專線：080-231528
http://www.timesisland.com.tw
E-mail: timesinfo@times19.com.tw

12/18/1997 中國時報



EPSON

3/30/1998



科技享樂主義



想像地球屋

毫釐之差 天壤之別 EPSON彩色噴墨印表機技高一籌



EPSON
精確點墨噴墨
印表機之噴頭

精確點墨噴墨技術 列印品質的新基準

EPSON 隆重推出全新領先的彩色噴墨列印技術標準 Perfect Picture Imaging System，採用劃時代精確點墨噴墨技術，其獨特的噴嘴設計比髮絲更纖細，讓列印效果清晰鮮明，列印品質直逼相片畫質。不同於傳統熱感式印表機將墨水加熱至沸騰吐出，精確點墨噴墨技術係以電子脈衝驅動噴嘴，墨水可以高速準確地噴出，墨點更小更均勻，提供優異色彩鮮豔、畫質佳麗兼具相片質感的列印畫像。

在 Perfect Picture Imaging System 中，除了精確點墨噴墨技術外，EPSON 同時研發快乾墨水，相片品質專用紙與真彩轉換技術，全面提升解析度及列印速度。

在不斷追求技術創新的同時，對環保的重視也是 EPSON 的重要使命。我們採買會產生有害二氧化碳的物料，並盡量回收可再生的零件。整台印表機僅有墨水匣需定期更換。在努力研發更卓越的產品與技術之際，亦不忘對環保盡一份心。

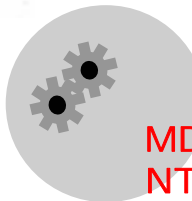


擁有 180 個
精確點墨噴墨噴嘴的印字頭
(實際大小)

Perfect Picture Imaging System

Seko Epson Corporation 3-3-3 Ono, Suway, Nagasaki, Japan
台灣總代理：精確點墨噴墨印表機有限公司，台北市南京東路二段 257 號 10 樓 電話：(02) 2711-7260

3/30/1998 中國時報



MDL
NTHU

- **Applications**

- + **Optical MEMS**

1. **Optical communication**
2. **Display**

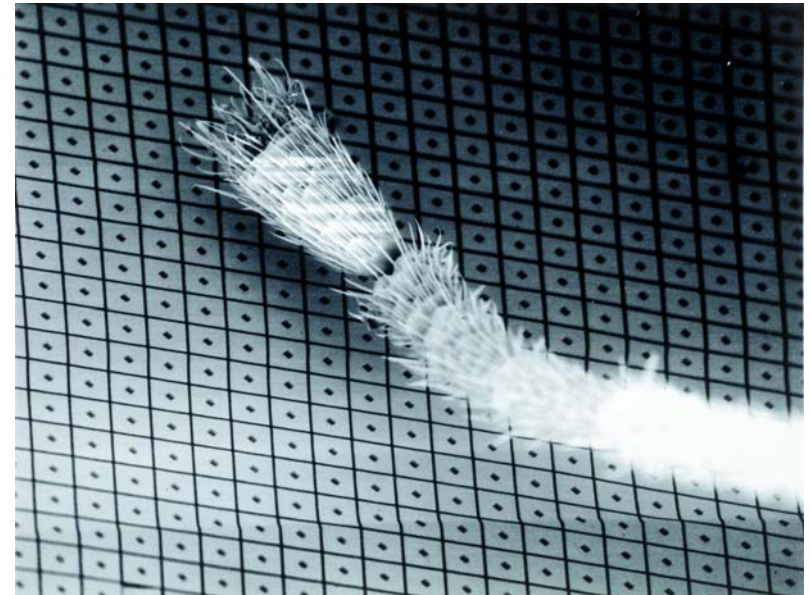
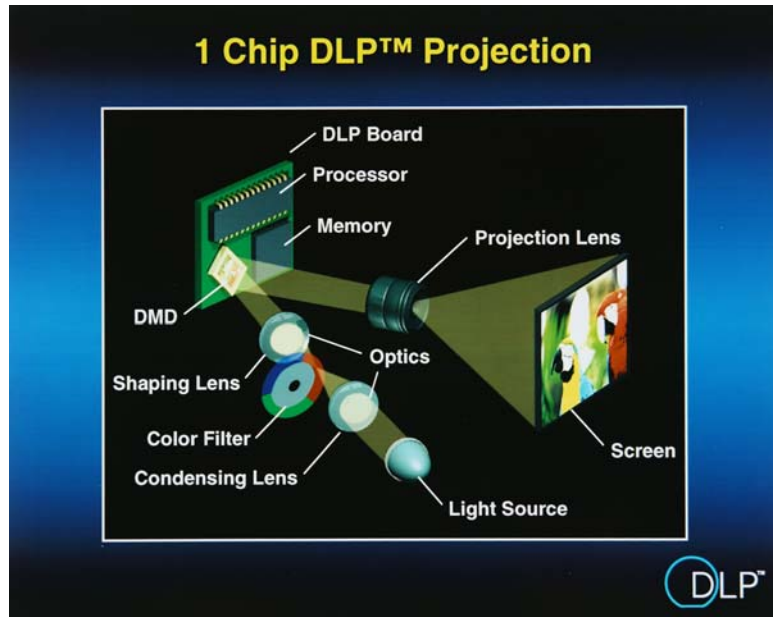
- + **RF MEMS**

1. **Wireless communication**

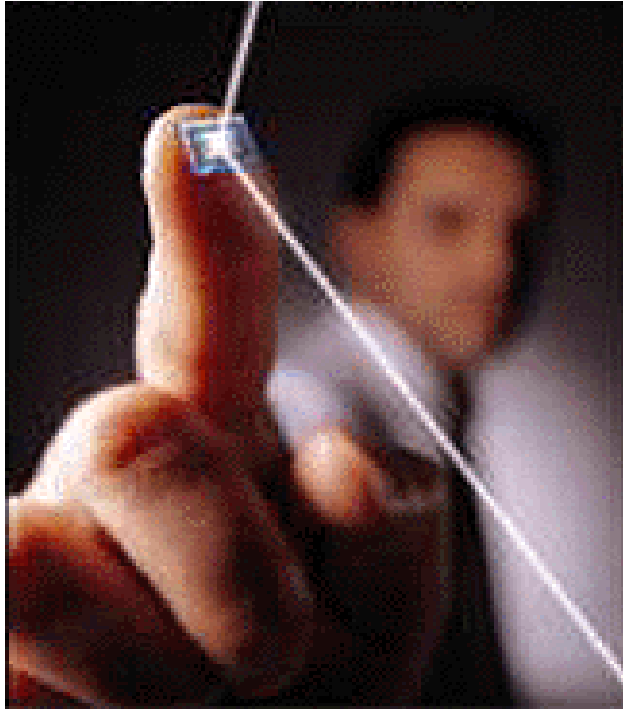
- + **Bio MEMS**

1. **Bio physics – hearing aid, manipulator, etc.**
2. **Bio chemistry – lab on chip**

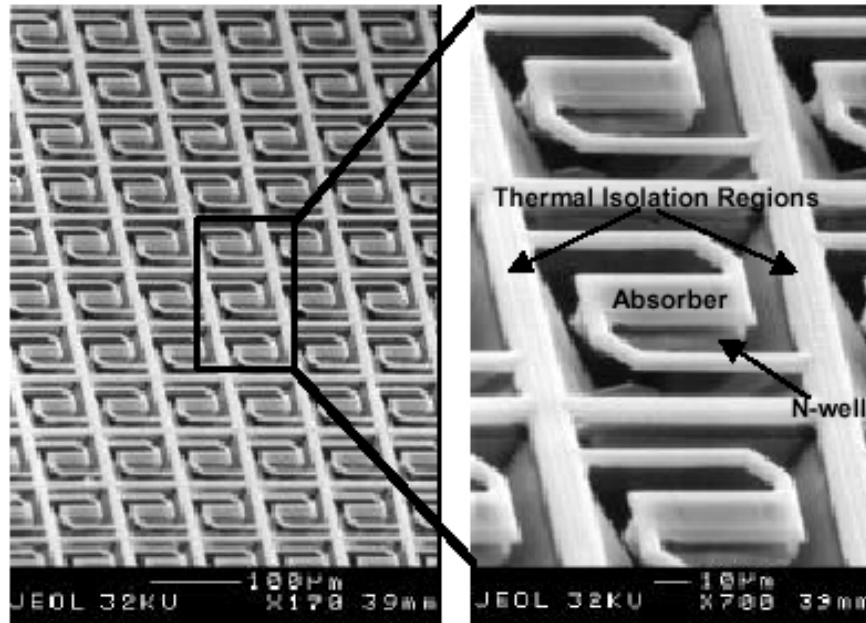
+ Optical MEMS - modulator (scanner, switch)



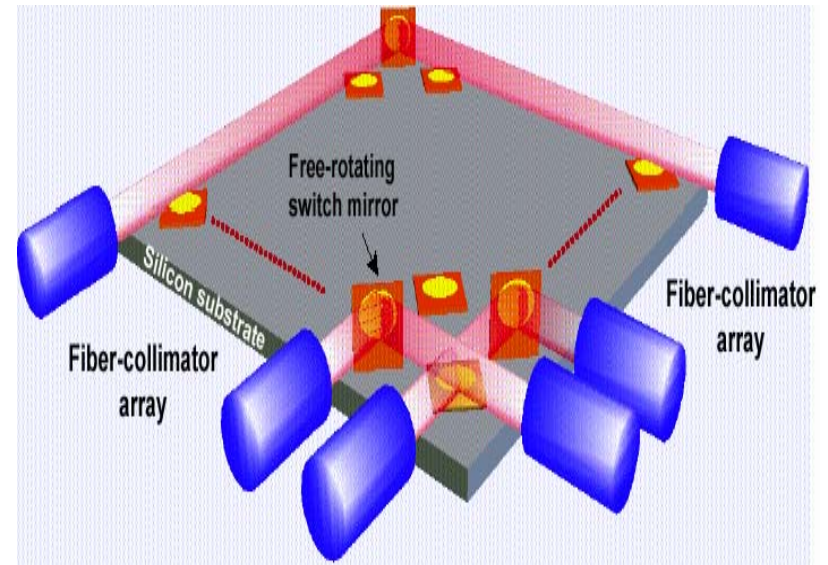
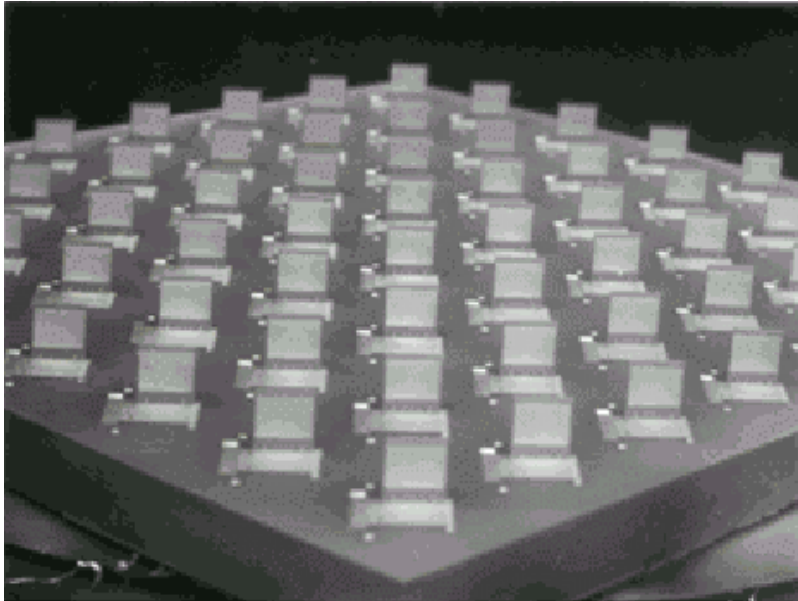
Digital mirror device by TI



Optical scanner for headmount display by Microvision Inc.

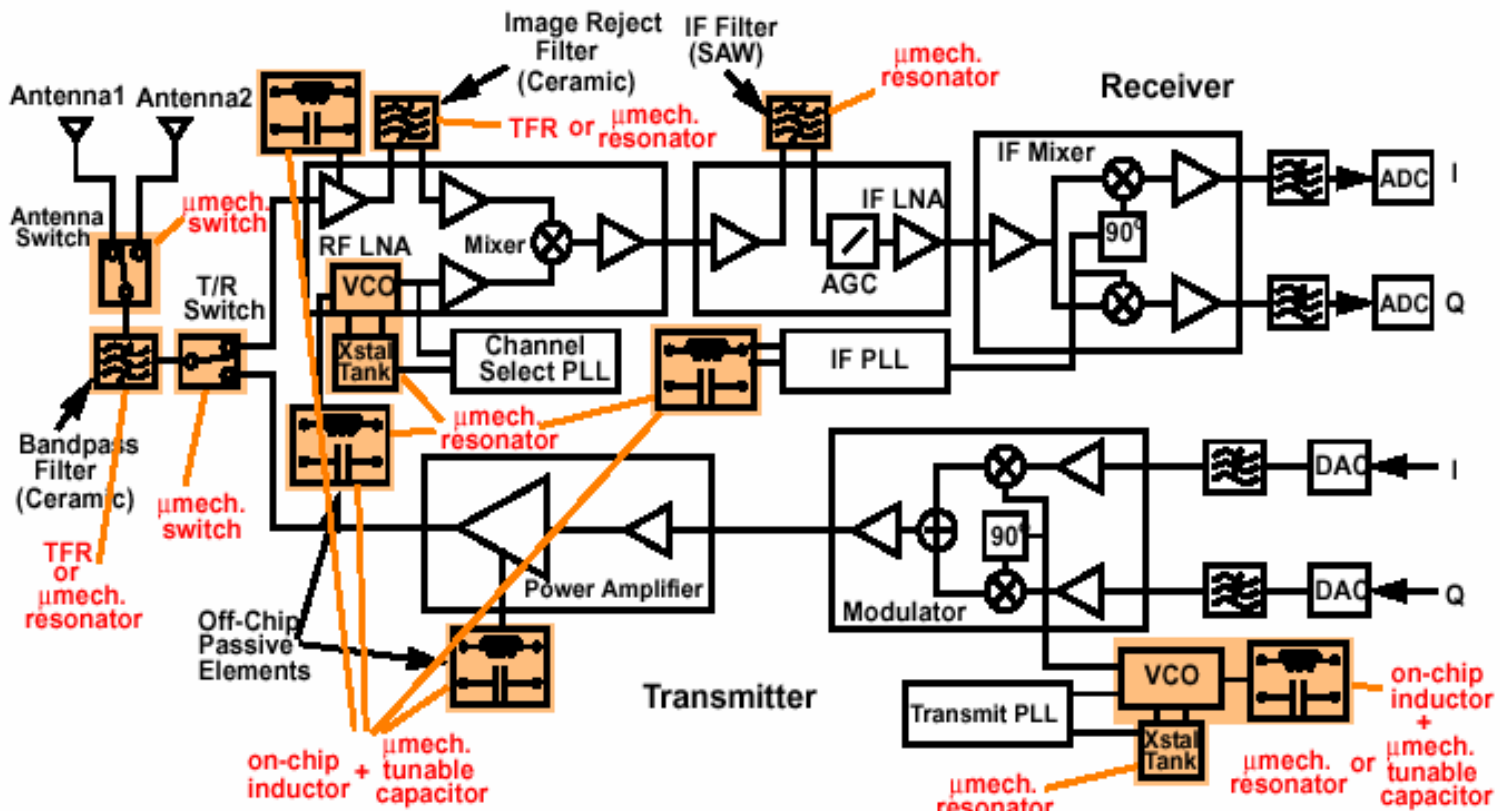


IR imager by Honeywell

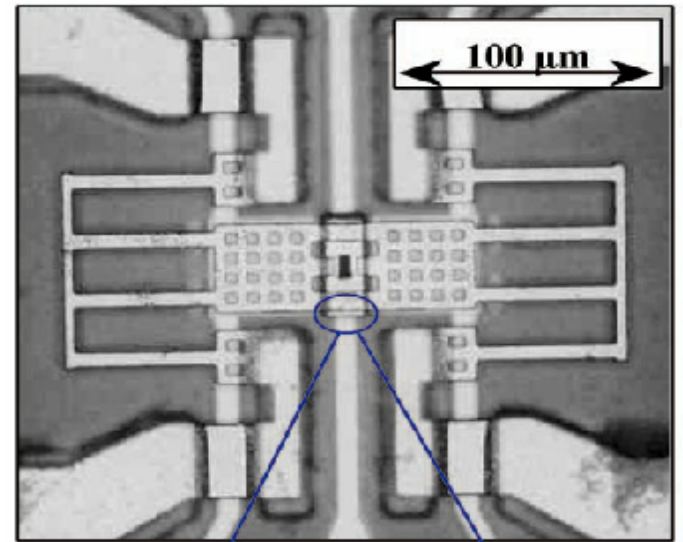
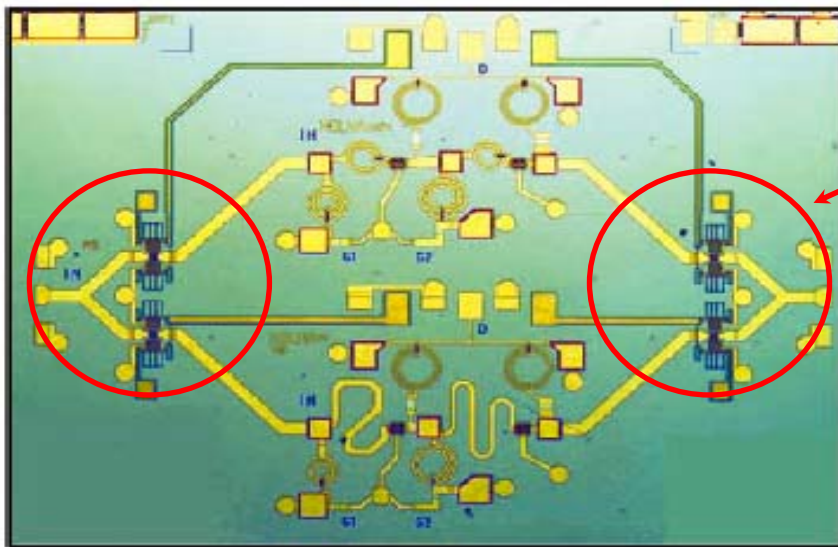


2D optical switch by OMM

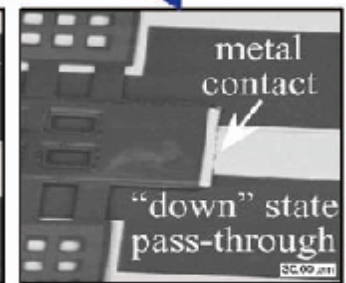
+ RF MEMS - switch, filter, oscillator



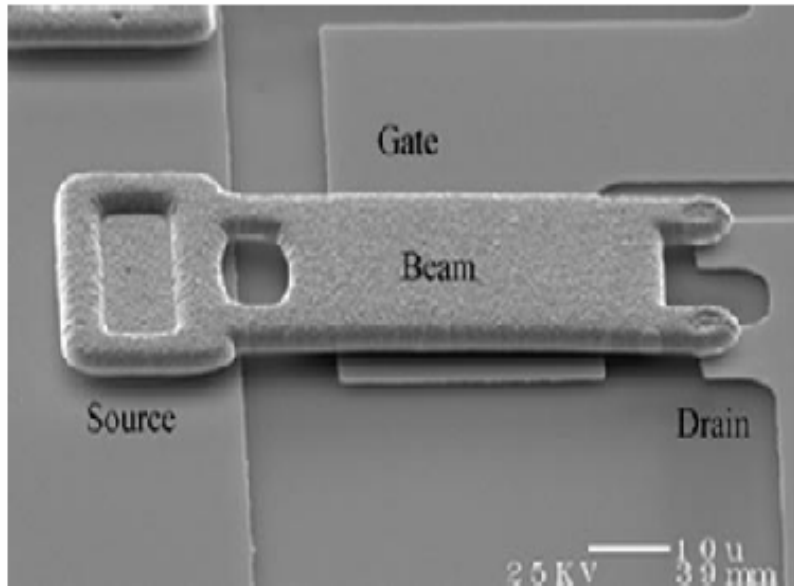
Nguyen, 1999



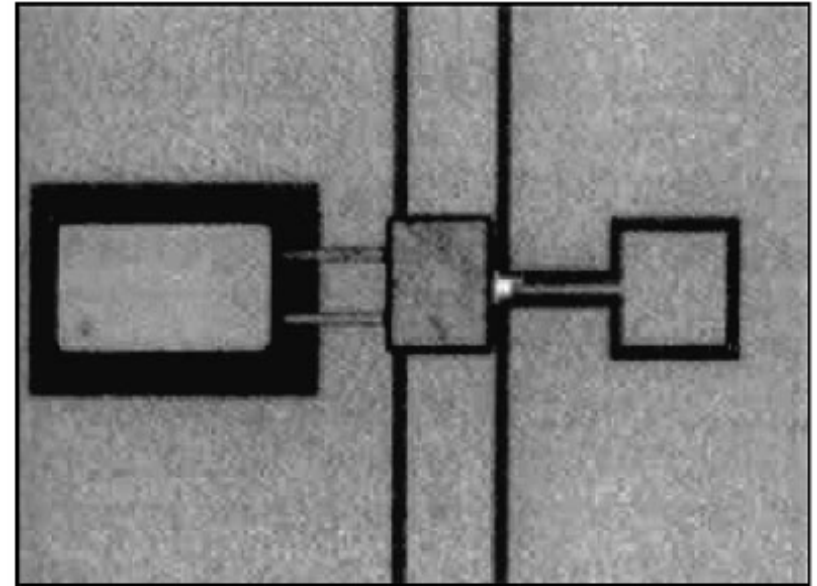
(a)



Micro switch by Rockwell Science Center



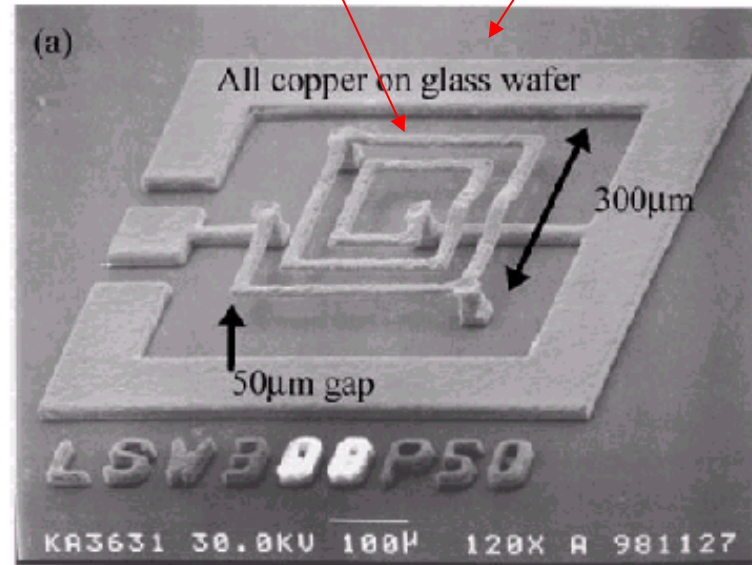
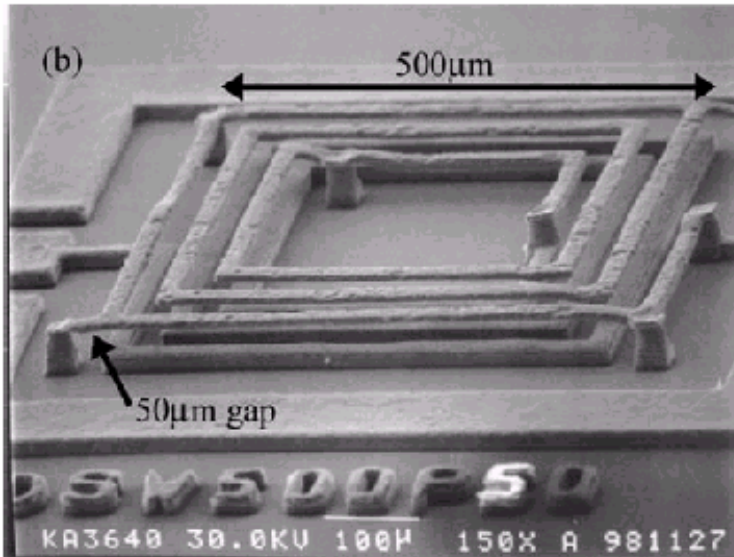
Micro switch by Northeastern U.



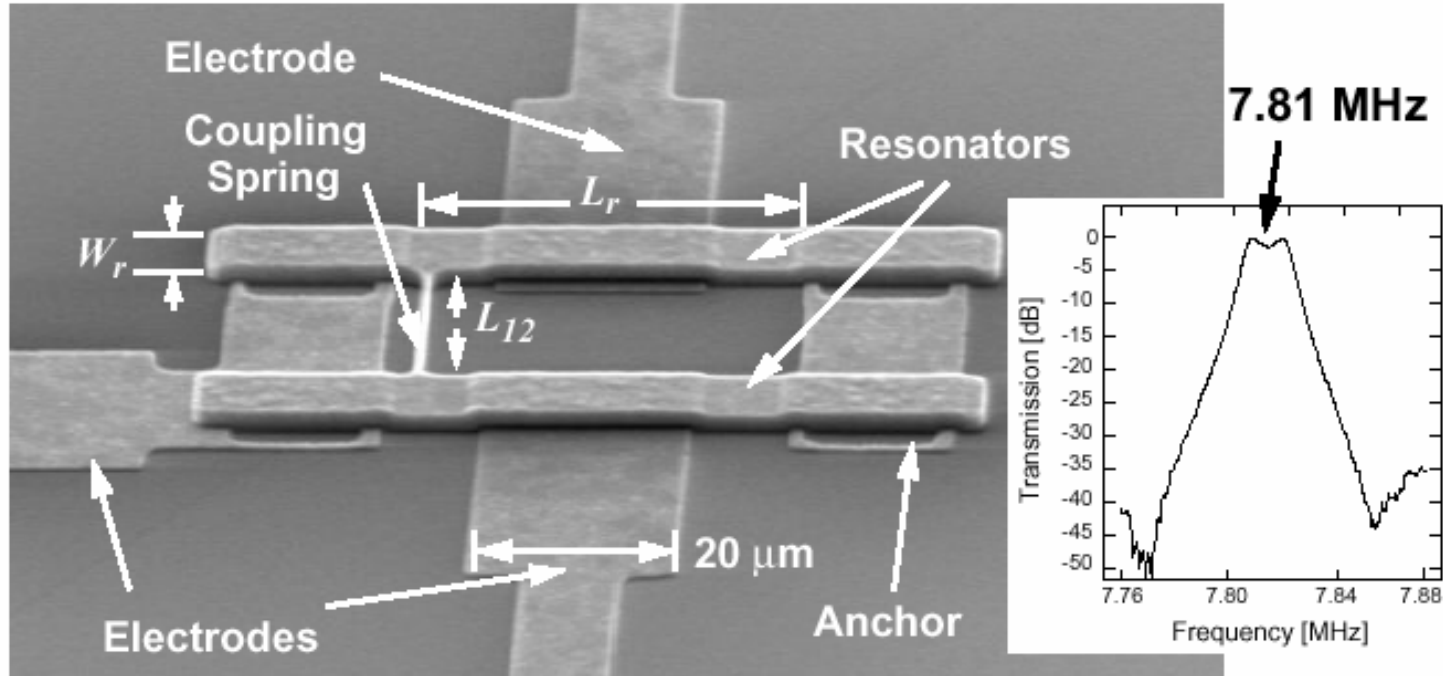
Micro switch by NEC

Cu spiral

Glass substrate



High-Q inductor by KAIST

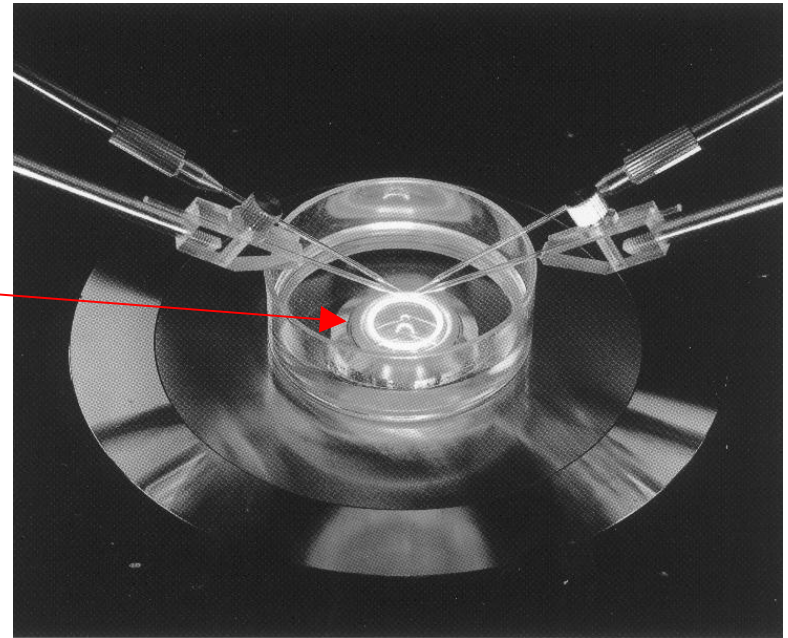
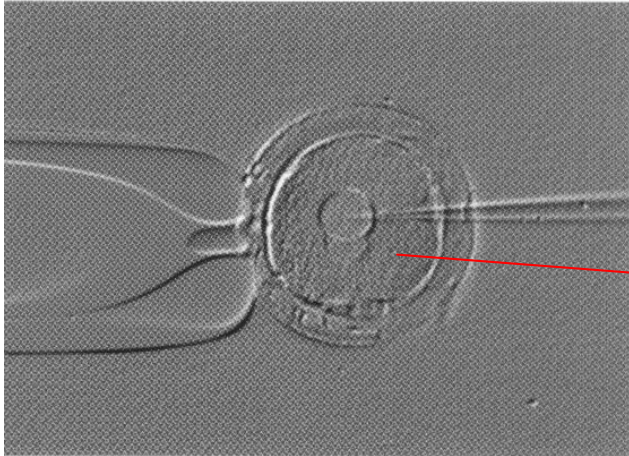


High frequency mechanical filter by U. of Michigan

+ Bio MEMS - DNA, lab on chip, μ TAS



DNA test by Caliper Tech



Bio-manipulator



Hearing aid

- **Applications**

- + **Automobile**

1. **pressure sensor - fuel system, hydraulic and air-flow systems**
2. **accelerometer - air bag, suspension system**
3. **gyroscope sensor - navigation system**

- + **Medical**

1. **pressure sensor - blood pressure, intrauterine pressure**
2. **microfluid system - drug dosage system, blood cell counting system**

- + **Data storage**

1. **accelerometer - impact detector**
2. **actuator - track positioning**
3. **suspension - recording head**

